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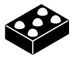
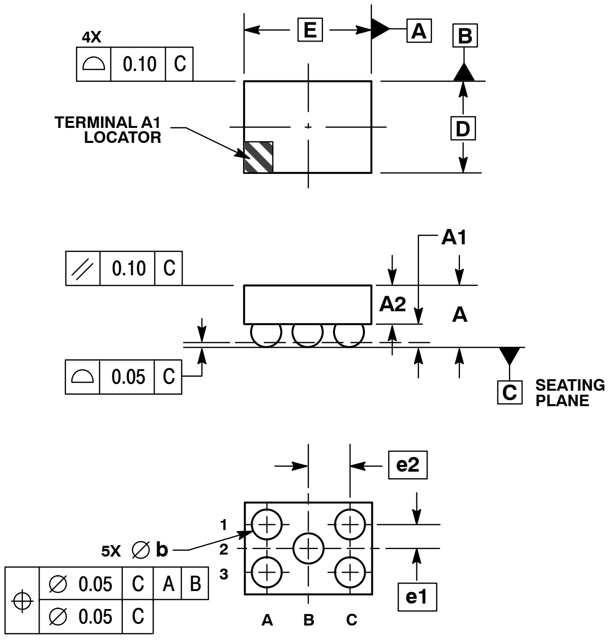
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SCALE 4:1

5 PIN FLIP−CHIP
CASE 499AY
ISSUE O

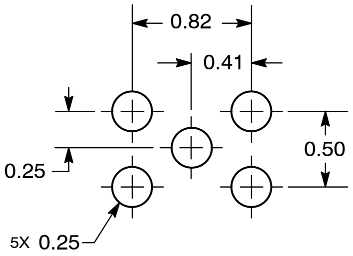
DATE 06 JUN 2007



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	**MIN**	**NOM**	**MAX**
A	0.475	0.530	0.585
A1	0.170	0.200	0.230
A2	0.305	0.330	0.355
b	0.220	0.250	0.270
D	1.028 BSC		
E	1.190 BSC		
e1	0.250 BSC		
e2	0.410 BSC		

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	**5 PIN FLIP−CHIP, 1.028X1.190**	**PAGE 1 OF 1**